



Material Content Data Sheet



Sales Product Name		IDH04SG60C		Issued		29. August 2013		
MA#		MA000629874						
Package		PG-TO220-2-1		Weight*		1966.14 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	siliconcarbide	409-21-2	0.817	0.04		416	
	noble metal	gold	7440-57-5	0.019	0.00		9	
	non noble metal	tin	7440-31-5	0.005	0.00	0.04	2	427
leadframe	non noble metal	iron	7439-89-6	0.753	0.04		383	
	inorganic material	phosphorus	7723-14-0	0.226	0.01		115	
wire	non noble metal	copper	7440-50-8	751.797	38.24	38.29	382373	382871
	non noble metal	aluminium	7429-90-5	0.166	0.01	0.01	85	85
encapsulation	organic material	carbon black	1333-86-4	9.112	0.46		4634	
	plastics	epoxy resin	-	100.227	5.10		50977	
	inorganic material	silicondioxide	60676-86-0	498.097	25.33	30.89	253338	308949
leadfinish	non noble metal	tin	7440-31-5	14.487	0.74	0.74	7368	7368
plating	non noble metal	nickel	7440-02-0	0.198	0.01		101	
	inorganic material	phosphorus	7723-14-0	0.000	0.00	0.01	0	101
heatspreader	inorganic material	phosphorus	7723-14-0	0.177	0.01		90	
	non noble metal	iron	7439-89-6	0.590	0.03		300	
	non noble metal	copper	7440-50-8	589.466	29.98	30.02	299809	300199
*deviation	< 10%				Sum in total:	100,00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com